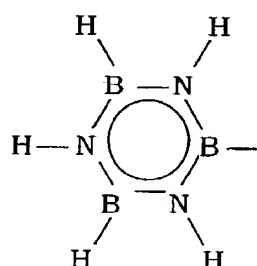


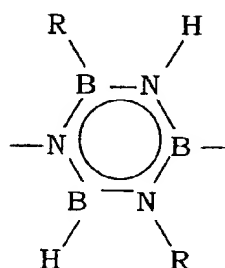
WHAT IS CLAIMED IS

good

1. A low dielectric constant material having thermal resistance, comprising borazine skeletal molecules shown by the following formula (1), (2), or (3) in an inorganic or organic material molecule.

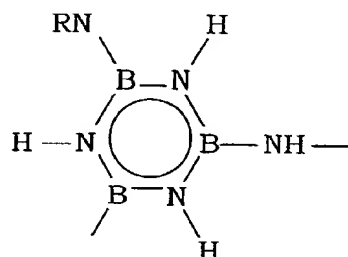


... (1)



R=H or borazynyl

... (2)



R=H₂, (borazynyl)₂, or H+borazynyl

... (3)

2. An insulation film ^{for use} between semiconductor layers, comprising the low dielectric constant material having thermal resistance of Claim 1.

1, 6, 8

3. A semiconductor device, comprising an insulation film between semiconductor layers comprising the low dielectric constant material having thermal resistance of Claim 1.

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